12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# # 20141029000
New Assembly Source and Transition to Center Pin Gate Mold for DLPC200ZEW
Information Only

Date: 10/31/2014
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for customer information only. Please note that implementation may occur immediately after notification.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20141029000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DLPC200ZEW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20141029000	**PCN Date:**	10/30/2014

Title:	New Assembly Source and Transition to Center Pin Gate Mold for DLPC200ZEW

Customer Contact:	DLP-PCN-team@list.ti.com	**Phone:**	(214) 567-4065	**Dept:**	DLP® CQE

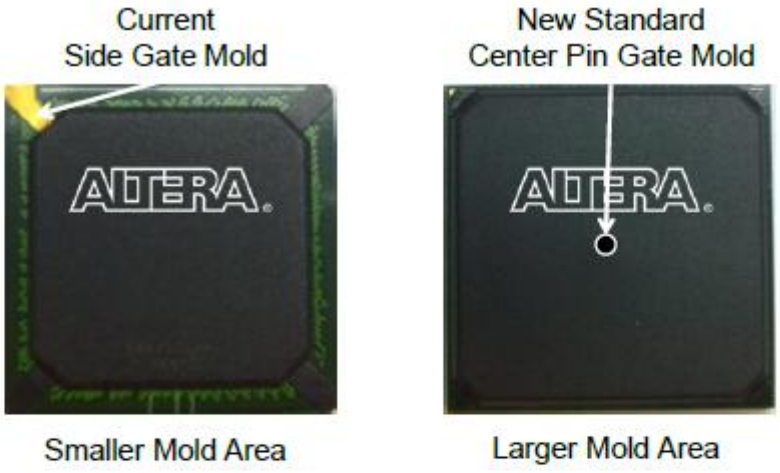
Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

TI has learned that in 2013, the DLPC200ZEW IC supplier introduced an additional assembly source (ASE) and transitioned to center pin gate mold and Sumitomo mold compound. Amkor will continue to be an assembly site, and Amkor has also changed to the center pin gate mold assembly method. The overall package dimensions will remain the same. The below picture illustrates the change. As of October 2014, TI has inventory of both package styles.



Further details of the change, including qualification data, can be observed here.

TI DLP® was unaware of this change and regrets that TI did not send a PCN before the change was implemented.

Reason for Change:
Assurance of Supply
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
There is a slight change to the package form as the mold compound extends to the edge of the substrate on the center pin gate mold package.
Changes to product identification resulting from this PCN:
There is a slight change to the package form as the mold compound extends to the edge of the substrate on the center pin gate mold package. Also, devices with the change will have a suffix "E" at the end of the date code marking.
Product Affected:
DLPC200ZEW, DLPC200ZEWCM

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
DLP® CQE PCN Team	DLP-PCN-Team@list.ti.com
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com